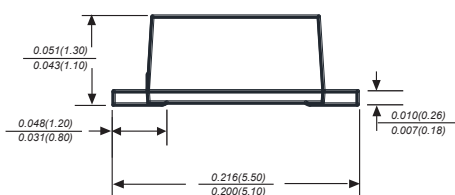
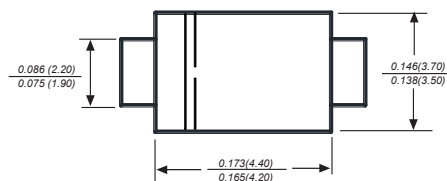


SURFACE MOUNT GENERAL PURPOSE SILICON RECTIFIER

Features

- ◆ For surface mounted applications
- ◆ Low profile package
- ◆ Glass Passivated Chip Junction
- ◆ Easy to pick and place
- ◆ Lead free in comply with EU RoHS 2011/65/EU directives

SMBF



Dimensions in inches and (millimeters)

Mechanical Data

Case : JEDEC SMBF molded plastic body

Terminals : Solderable per MIL-STD-750, Method 2026

Polarity : Polarity symbol marking on body

Mounting Position : Any

Weight : 0.002 ounce, 0.057 grams

Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	S5ABF	S5BBF	S5DBF	S5GBF	S5JBF	S5KBF	S5MBF	UNITS
Marking Code		MDD S5AB	MDD S5BB	MDD S5DB	MDD S5GB	MDD S5JB	MDD S5KB	MDD S5MB	
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current at $T_L=65^\circ\text{C}$	$I_{(AV)}$	5.0							A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	125							A
Maximum instantaneous forward voltage at 5.0A	V_F	1.10							V
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=125^\circ\text{C}$	I_R	5.0 150.0							μA
Typical junction capacitance (NOTE 1)	C_J	45.0							pF
Typical thermal resistance (NOTE 2)	$R_{\theta JA}$	40.0							$^\circ\text{C}/\text{W}$
Operating junction and storage temperature range	T_J, T_{STG}	-55 to +150							$^\circ\text{C}$

Note: 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
 2. P.C.B. mounted with 0.5x0.5" (12.7x12.7mm) copper pad areas

Typical Characteristics

Fig.1 Forward Current Derating Curve

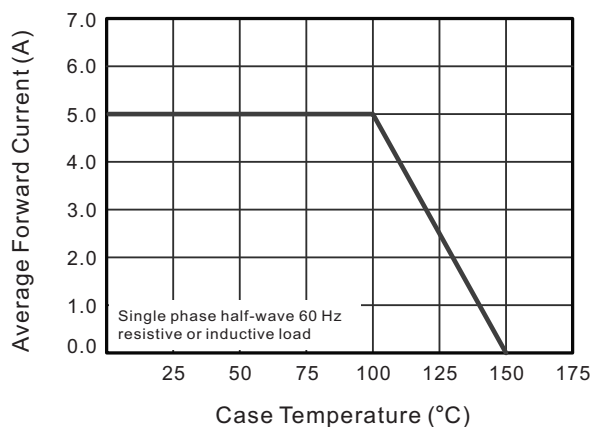


Fig.2 Typical Reverse Characteristics

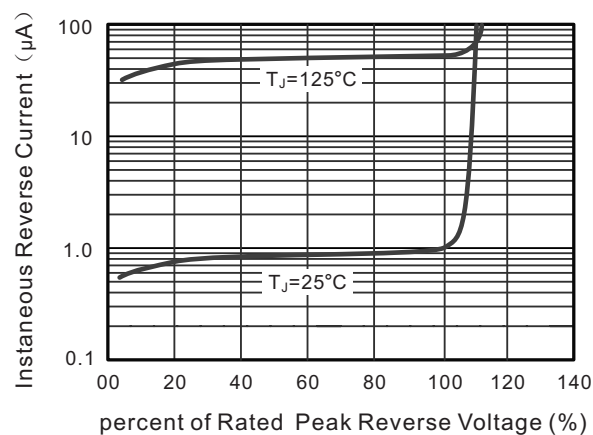


Fig.3 Typical Forward Characteristic

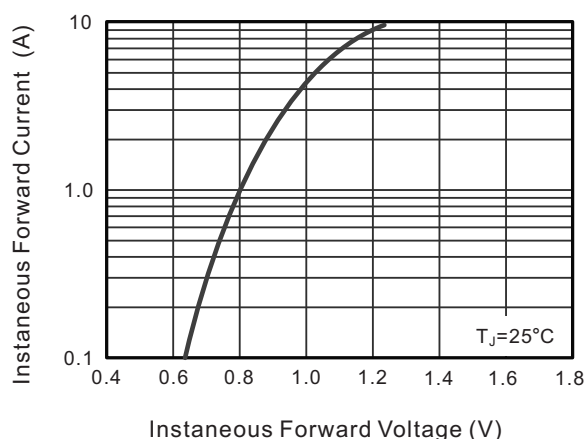


Fig.4 Typical Junction Capacitance

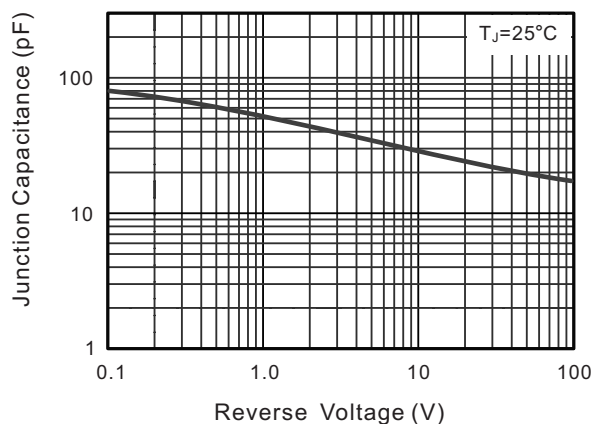
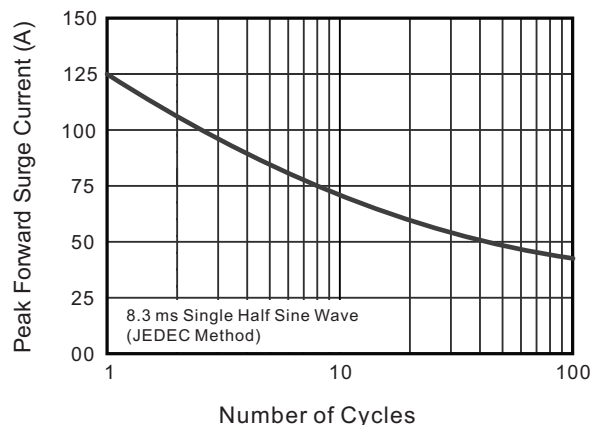
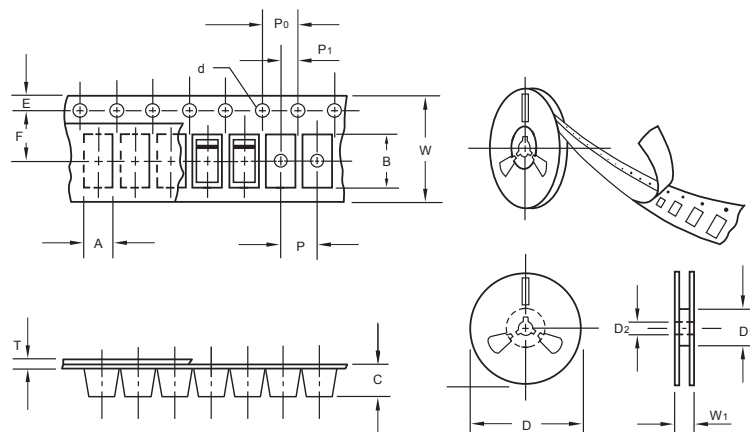


Fig.6 Maximum Non-Repetitive Peak Forward Surge Current



The curve above is for reference only.

Packing information



unit:mm

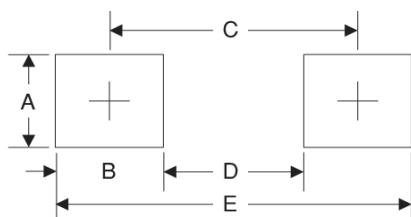
Item	Symbol	Tolerance	SMBF
Carrier width	A	0.1	3.81
Carrier length	B	0.1	5.61
Carrier depth	C	0.1	1.60
Sprocket hole	d	0.05	1.50
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D1	min	50.00
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	5.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.30
Tape width	W	0.3	12.00
Reel width	W1	1.0	12.30

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (mm)	BOX (pcs)	INNER BOX (mm)	REEL DIA. (mm)	CARTON SIZE (mm)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMBF	13"	5,000	4.0	10,000	190*190*41	330	365*365*360	80,000	14.0

Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	2.54	0.100
B	1.8	0.071
C	4.8	0.189
D	3.0	0.118
E	6.6	0.260